





# AND156EOP

## InGaAIP High Brightness Amber Light Emission T-1 3/4 Package (5 mm)

#### **Features**

- Peak wavelength ( $\lambda p = 612 \text{ nm}$ ) high bright emission
- All plastic mold type, clear colorless lens
- Low drive current: 15 to 20 mA DC
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation
- High power luminous intensity
- Suitable for Outdoor Message Signboards
- High reliability

## Maximum Ratings (T = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	30	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	75	mW
Operating Temperature Range	T <sub>Opr</sub>	-30 to 85	°C
Storage Temperature Range	T <sub>Stg</sub>	-40 to 120	°C

### **Electro-Optical Characteristics (T = 25°C)**

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	_	1.95	2.4	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4 V	_	-	50	μA
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20 mA	300	800	-	mcd
Peak Emission Wavelength	l <sub>P</sub>	I <sub>F</sub> = 20 mA	_	612	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20 mA	_	15	-	nm
Dominant Wavelength	λd	I <sub>F</sub> = 20 mA	_	605	-	nm
Full Viewing Angle	θ	I <sub>V</sub> = 1/2 Peak	_	30	-	degree

#### Precaution

Please be careful of the following:

- 1. Soldering temperature: 260°C max
  - Soldering time: 3 sec. max
  - Soldering portion of lead: up to 2 mm from the body of the device
- 2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.















